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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51103adfl-30

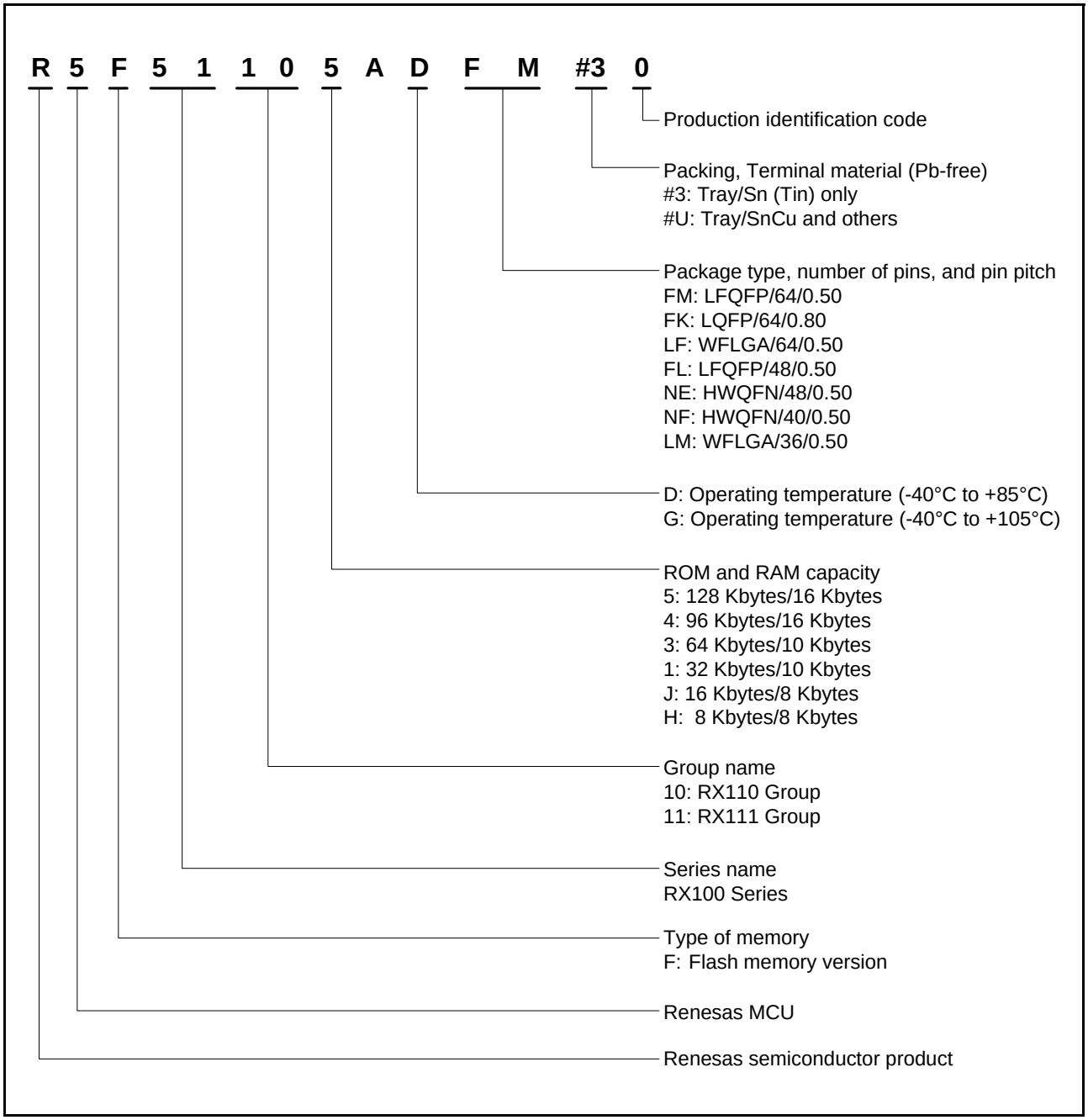
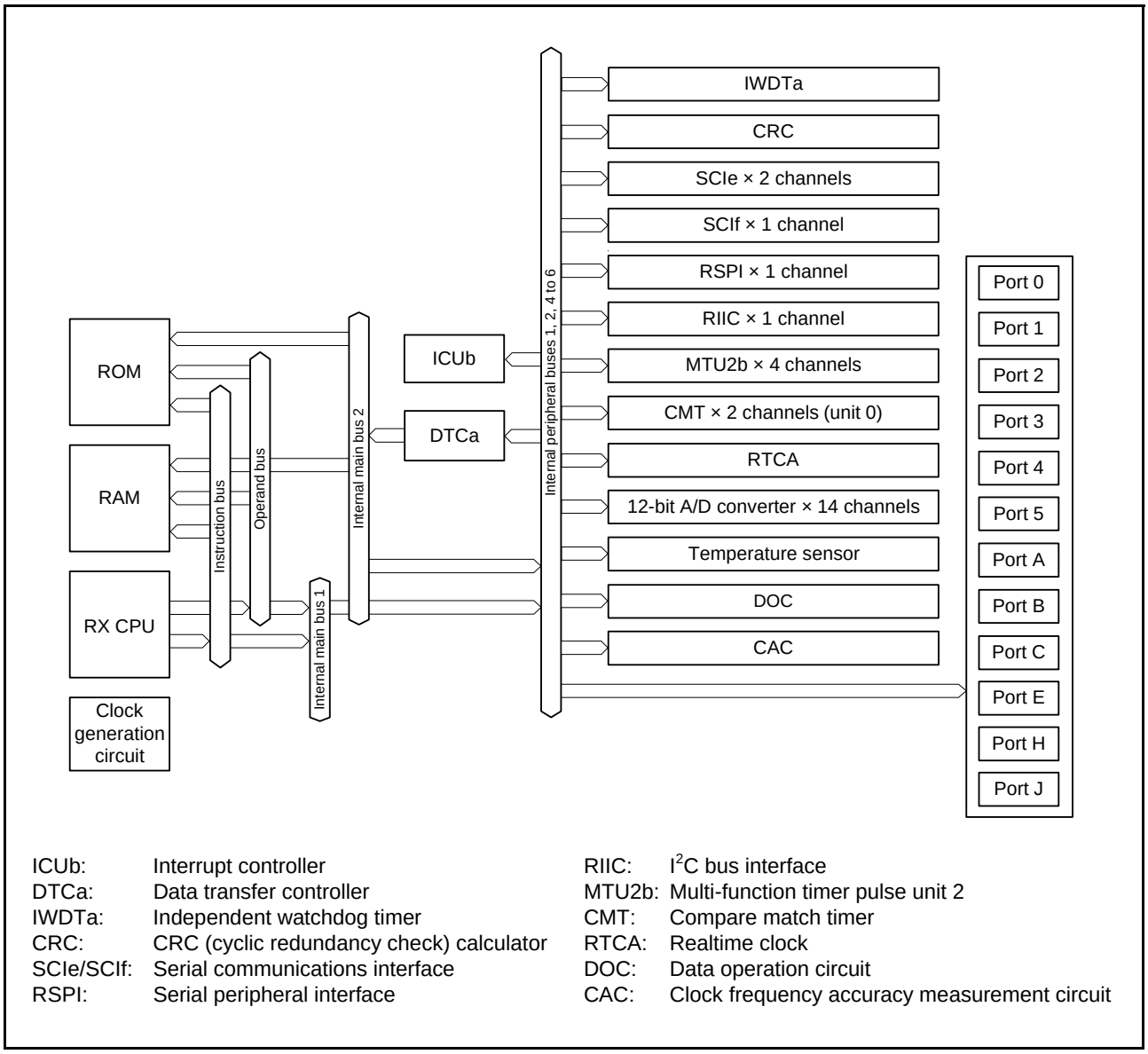


Figure 1.1 How to Read the Product Part No., Memory Capacity, and Package Type

1.3 Block Diagram

Figure 1.2 shows a block diagram.



ICUb:	Interrupt controller	RIIC:	I^2C bus interface
DTCa:	Data transfer controller	MTU2b:	Multi-function timer pulse unit 2
IWDTa:	Independent watchdog timer	CMT:	Compare match timer
CRC:	CRC (cyclic redundancy check) calculator	RTCA:	Realtime clock
SCIe/SCIf:	Serial communications interface	DOC:	Data operation circuit
RSPI:	Serial peripheral interface	CAC:	Clock frequency accuracy measurement circuit

Figure 1.2 Block Diagram

1.4 Pin Functions

Table 1.4 lists the pin functions.

Table 1.4 Pin Functions (1/3)

Classifications	Pin Name	I/O	Description
Power supply	VCC	Input	Power supply pin. Connect it to the system power supply.
	VCL	—	Connect this pin to the VSS pin via the 4.7 µF smoothing capacitor used to stabilize the internal power supply. Place the capacitor close to the pin.
	VSS	Input	Ground pin. Connect it to the system power supply (0 V).
Analog power supply	AVCC0	Input	Analog voltage supply pin for the 12-bit A/D converter. Connect this pin to VCC when not using the 12-bit A/D converter.
	AVSS0	Input	Analog ground pin for the 12-bit A/D converter. Connect this pin to VSS when not using the 12-bit A/D converter.
	VREFH0	Input	Analog reference voltage supply pin for the 12-bit A/D converter. Connect this pin to VCC when not using the 12-bit A/D converter.
	VREFL0	Input	Analog reference ground pin for the 12-bit A/D converter. Connect this pin to VSS when not using the 12-bit A/D converter.
Clock	XTAL	Output/ Input *1	Pins for connecting a crystal resonator. An external clock can be input through the XTAL pin.
	EXTAL	Input	
	XCIN	Input	Input/output pins for the sub-clock oscillator. Connect a crystal resonator between XCIN and XCOUT.
	XCOUT	Output	
	CLKOUT	Output	Clock output pin.
Operating mode control	MD	Input	Pin for setting the operating mode. The signal levels on this pin must not be changed during operation.
System control	RES#	Input	Reset pin. This LSI enters the reset state when this signal goes low.
CAC	CACREF	Input	Input pin for the clock frequency accuracy measurement circuit.
On-chip emulator	FINED	I/O	FINE interface pin.
LVD	CMPA2	Input	Detection target voltage pin for voltage detection 2.
Interrupts	NMI	Input	Non-maskable interrupt request pin.
	IRQ0 to IRQ7	Input	Interrupt request pins.
Multi-function timer pulse unit 2	MTIOC0A, MTIOC0B MTIOC0C, MTIOC0D	I/O	The TGRA0 to TGRD0 input capture input/output compare output/PWM output pins.
	MTIOC1A, MTIOC1B	I/O	The TGRA1 and TGRB1 input capture input/output compare output/PWM output pins.
	MTIOC2A, MTIOC2B	I/O	The TGRA2 and TGRB2 input capture input/output compare output/PWM output pins.
	MTIC5U, MTIC5V, MTIC5W	Input	The TGRU5, TGRV5, and TGRW5 input capture input/external pulse input pins.
	MTCLKA, MTCLKB, MTCLKC, MTCLKD	Input	Input pins for the external clock.
Realtime clock	RTCOUT	Output	Output pin for the 1-Hz/64-Hz clock.
Serial communications interface (SCIe)	• Asynchronous mode/clock synchronous mode		
	SCK1, SCK5	I/O	Input/output pins for the clock.
	RXD1, RXD5	Input	Input pins for receiving data.
	TXD1, TXD5	Output	Output pins for transmitting data.
	CTS1#, CTS5#	Input	Input pins for controlling the start of transmission and reception.
	RTS1#, RTS5#	Output	Output pins for controlling the start of transmission and reception.

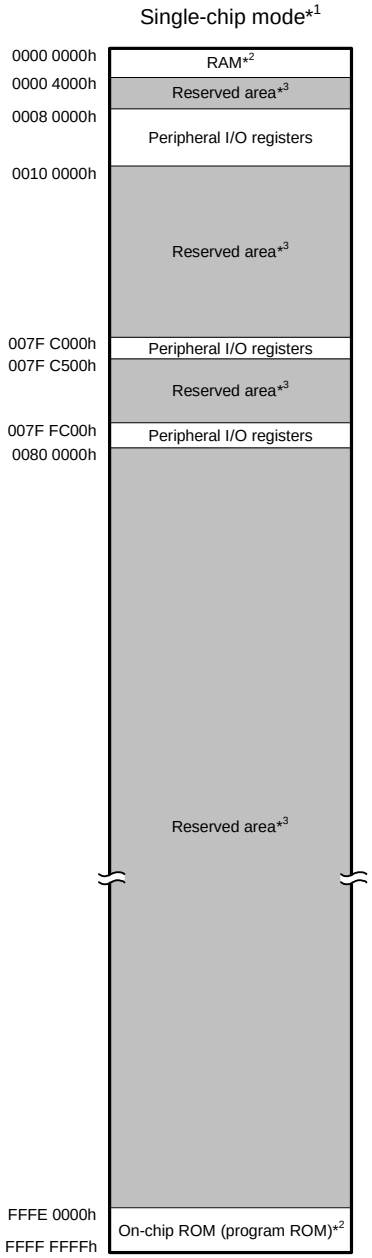
Table 1.6 List of Pins and Pin Functions (64-Pin WFLGA) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
A1	AVSS0				
A2	AVCC0				
A3	VREFH0	PJ6*1			
A4	VREFL0	PJ7*1			
A5		P43*1			AN003
A6		P46*1			AN006
A7		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
A8		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
B1	XCOUT				
B2		P03			
B3		P40*1			AN000
B4		P42*1			AN002
B5		P44*1			AN004
B6		PE6			IRQ6/AN014
B7		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
B8		PE4	MTIOC1A	MOSIA	IRQ4/AN012
C1	XCIN	PH7			
C2		P05			
C3		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
C4		P41*1			AN001
C5		PE7			IRQ7/AN015
C6		PE5	MTIOC2B		IRQ5/AN013
C7		PA1	MTIOC0B/MTCLKC/ RTCOUT	SCK5/SSLA2	
C8		PA0		SSLA1	CACREF
D1	RES#				
D2		P30		RXD1/SMISO1/SSCL1	IRQ0
D3		P26	MTIOC2A	TXD1/SMOSI1/SSDA1	
D4		PE0	MTIOC2A	SCK12	IRQ0/AN008
D5		PA6	MTIC5V/MTIOC2A/MTCLKB	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
D6		PA4	MTIC5U/MTIOC2B/MTCLKA	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
D7		PA3	MTIOC0D/MTCLKD/ MTIOC1B	RXD5/SMISO5/SSCL5/MISOA	IRQ6
D8	VSS				
E1	XTAL				
E2	MD				FINED
E3		P31		CTS1#/RTS1#/SS1#	IRQ1
E4		P55			
E5		PB3	MTIOC0A		
E6		PB1	MTIOC0C		IRQ4
E7		PB0	MTIC5W/MTIOC0C/ RTCOUT	SCL0/RSPCKA	IRQ2/ADTRG0#
E8	VCC				
F1	EXTAL				
F2		P32	MTIOC0C/RTCOUT		IRQ2
F3		P35			NMI
F4		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12/ SSLA0	IRQ4

Table 1.8 List of Pins and Pin Functions (40-Pin HWQFN)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, RTC)	Communication (SCIe, SCIf, RSPI, RIIC)	Others
1		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/ CACREF/ADTRG0#
2		P26	MTIOC2A	TXD1/SMOSI1/SSDA1	
3	MD				FINED
4	RES#				
5		P35			NMI
6	XTAL				
7	EXTAL				
8	VCL				
9	VSS				
10	VCC				
11		P32	MTIOC0C		IRQ2
12		P17	MTIOC0C	SCK1/MISOA/SDA0/RXD12/RXDX12/ SMISO12/SSCL12	IRQ7
13		P16		TXD1/SMOSI1/SSDA1/SCL0/MOSIA	IRQ6/ADTRG0#
14		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
15		P14	MTIOC0A/MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/SSDA12	IRQ4
16		PH3	MTIOC1A		
17		PH2			IRQ1
18		PH1			IRQ0
19		PH0	MTIOC1B		CACREF
20		PC4	MTCLKC	SCK5/SSLA0	IRQ2/CLKOUT
21		PB3	MTIOC0A		
22	VCC				
23		PB0	MTIOC0C/MTIC5W	SCL0/RSPCKA	IRQ2/ADTRG0#
24	VSS				
25		PA6	MTIOC2A/MTIC5V/MTCLKB	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
26		PA4	MTIOC2B/MTIC5U/MTCLKA	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
27		PA3	MTIOC0D/MTIOC1B/ MTCLKD	RXD5/SMISO5/SSCL5/MISOA	IRQ6
28		PA1	MTIOC0B/MTCLKC	SCK5/SSLA2	
29		PE4	MTIOC1A	MOSIA	IRQ4/AN012
30		PE3	MTIOC0A/MTIOC1B	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
31		PE2		RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
32		PE1		TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
33		PE0	MTIOC2A	SCK12	IRQ0/AN008
34		P46*1			AN006
35		P42*1			AN002
36		P41*1			AN001
37	VREFL0	PJ7*1			
38	VREFH0	PJ6*1			
39	AVSS0				
40	AVCC0				

Note 1. The power source of the I/O buffer for these pins is AVCC0.



Note 1. The address space in boot mode is the same as the address space in single-chip mode.
Note 2. The capacity of ROM/RAM differs depending on the products.

ROM (bytes)		RAM (bytes)	
Capacity	**Address**	**Capacity**	**Address**
128 K	FFFE 0000h to FFFF FFFFh	16 K	0000 0000h to 0000 3FFFh
96 K	FFFE 8000h to FFFF FFFFh		
64 K	FFFF 0000h to FFFF FFFFh	10 K	0000 0000h to 0000 27FFh
32 K	FFFF 8000h to FFFF FFFFh		
16 K	FFFF C000h to FFFF FFFFh	8 K	0000 0000h to 0000 1FFFh
8 K	FFFF E000h to FFFF FFFFh		

Note:See Table 1.3, List of Products, for the product type name.

Note 3. Reserved areas should not be accessed.

Figure 3.1 Memory Map

Table 4.1 List of I/O Registers (Address Order) (8/13)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 9034h	S12AD	A/D Data Register 10	ADDR10	16	16	2 or 3 PCLKB
0008 9036h	S12AD	A/D Data Register 11	ADDR11	16	16	2 or 3 PCLKB
0008 9038h	S12AD	A/D Data Register 12	ADDR12	16	16	2 or 3 PCLKB
0008 903Ah	S12AD	A/D Data Register 13	ADDR13	16	16	2 or 3 PCLKB
0008 903Ch	S12AD	A/D Data Register 14	ADDR14	16	16	2 or 3 PCLKB
0008 903Eh	S12AD	A/D Data Register 15	ADDR15	16	16	2 or 3 PCLKB
0008 9060h	S12AD	A/D Sampling State Register 0	ADSSTR0	8	8	2 or 3 PCLKB
0008 9061h	S12AD	A/D Sampling State Register L	ADSSTRL	8	8	2 or 3 PCLKB
0008 9070h	S12AD	A/D Sampling State Register T	ADSSTRT	8	8	2 or 3 PCLKB
0008 9071h	S12AD	A/D Sampling State Register O	ADSSTRO	8	8	2 or 3 PCLKB
0008 9073h	S12AD	A/D Sampling State Register 1	ADSSTR1	8	8	2 or 3 PCLKB
0008 9074h	S12AD	A/D Sampling State Register 2	ADSSTR2	8	8	2 or 3 PCLKB
0008 9075h	S12AD	A/D Sampling State Register 3	ADSSTR3	8	8	2 or 3 PCLKB
0008 9076h	S12AD	A/D Sampling State Register 4	ADSSTR4	8	8	2 or 3 PCLKB
0008 9078h	S12AD	A/D Sampling State Register 6	ADSSTR6	8	8	2 or 3 PCLKB
0008 A020h	SCI1	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 A021h	SCI1	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 A022h	SCI1	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 A023h	SCI1	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 A024h	SCI1	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 A025h	SCI1	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 A026h	SCI1	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 A027h	SCI1	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 A028h	SCI1	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 A029h	SCI1	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 A02Ah	SCI1	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 A02Bh	SCI1	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 A02Ch	SCI1	I^2C Status Register	SISR	8	8	2 or 3 PCLKB
0008 A02Dh	SCI1	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 A0A0h	SCI5	Serial Mode Register	SMR	8	8	2 or 3 PCLKB
0008 A0A1h	SCI5	Bit Rate Register	BRR	8	8	2 or 3 PCLKB
0008 A0A2h	SCI5	Serial Control Register	SCR	8	8	2 or 3 PCLKB
0008 A0A3h	SCI5	Transmit Data Register	TDR	8	8	2 or 3 PCLKB
0008 A0A4h	SCI5	Serial Status Register	SSR	8	8	2 or 3 PCLKB
0008 A0A5h	SCI5	Receive Data Register	RDR	8	8	2 or 3 PCLKB
0008 A0A6h	SCI5	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB
0008 A0A7h	SCI5	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB
0008 A0A8h	SCI5	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB
0008 A0A9h	SCI5	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB
0008 A0AAh	SCI5	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB
0008 A0ABh	SCI5	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB
0008 A0ACh	SCI5	I^2C Status Register	SISR	8	8	2 or 3 PCLKB
0008 A0ADh	SCI5	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB
0008 B000h	CAC	CAC Control Register 0	CACR0	8	8	2 or 3 PCLKB
0008 B001h	CAC	CAC Control Register 1	CACR1	8	8	2 or 3 PCLKB
0008 B002h	CAC	CAC Control Register 2	CACR2	8	8	2 or 3 PCLKB
0008 B003h	CAC	CAC Interrupt Request Enable Register	CAICR	8	8	2 or 3 PCLKB
0008 B004h	CAC	CAC Status Register	CASTR	8	8	2 or 3 PCLKB
0008 B006h	CAC	CAC Upper-Limit Value Setting Register	CAULVR	16	16	2 or 3 PCLKB
0008 B008h	CAC	CAC Lower-Limit Value Setting Register	CALLVR	16	16	2 or 3 PCLKB
0008 B00Ah	CAC	CAC Counter Buffer Register	CACNTBR	16	16	2 or 3 PCLKB
0008 B080h	DOC	DOC Control Register	DOCR	8	8	2 or 3 PCLKB

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Conditions: VSS = AVSS0 = VREFL0 = 0 V

Item		Symbol	Value	Unit
Power supply voltage		VCC	–0.3 to +4.6	V
Input voltage	Ports for 5 V tolerant*1	V_{in}	–0.3 to +6.5	V
	Ports P40 to P44, P46, ports PJ6, PJ7	V_{in}	–0.3 to AVCC0 +0.3	V
	Ports other than above	V_{in}	–0.3 to VCC +0.3	V
Reference power supply voltage		VREFH0	–0.3 to AVCC0 +0.3	V
Analog power supply voltage		AVCC0	–0.3 to +4.6	V
Analog input voltage		V_{AN}	–0.3 to AVCC0 + 0.3 (when AN000 to AN004 and AN006 used) –0.3 to VCC + 0.3 (when AN008 to AN015 used)	V
Operating temperature*2		T_{opr}	–40 to +85 –40 to +105	°C
Storage temperature		T_{stg}	–55 to +125	°C

Caution: Permanent damage to the MCU may result if absolute maximum ratings are exceeded.
To preclude any malfunctions due to noise interference, insert capacitors of high frequency characteristics between the VCC and VSS pins, between the AVCC0 and AVSS0 pins, and between the VREFH0 and VREFL0 pins. Place capacitors of about 0.1 µF as close as possible to every power supply pin and use the shortest and heaviest possible traces. Also, connect capacitors as stabilization capacitance.

Connect the VCL pin to a VSS pin via a 4.7 µF capacitor. The capacitor must be placed close to the pin, refer to section 5.9.1, Connecting VCL Capacitor and Bypass Capacitors.

Do not input signals or an I/O pull-up power supply to ports other than 5-V tolerant ports while the device is not powered. The current injection that results from input of such a signal or I/O pull-up may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements.
If input voltage (within the specified range from -0.3 to + 6.5V) is applied to 5-V tolerant ports, it will not cause problems such as damage to the MCU.

Note 1. Ports P16, P17, PA6, and PB0 are 5 V tolerant.
Note 2. The upper limit of operating temperature is 85°C or 105°C, depending on the product. For details, refer to 1.2 List of Products.

Table 5.2 Recommended Operating Conditions

Item	Symbol	Min.	Typ.	Max.	Unit
Power supply voltages	VCC*1	1.8	—	3.6	V
	VSS	—	0	—	V
Analog power supply voltages	AVCC0*1, *2	1.8	—	3.6	V
	AVSS0	—	0	—	V
	VREFH0	1.8	—	AVCC0	V
	VREFL0	—	0	—	V

Note 1. Supply AVCC0 simultaneously with or after supplying VCC.
Note 2. Refer to section 27.6.10, Voltage Range of Analog Power Supply Pins in the User's Manual: Hardware to determine the AVCC0 voltage.

Table 5.4 DC Characteristics (2)

Conditions: 1.8 V ≤ VCC < 2.7 V, 1.8 V ≤ AVCC0 < 2.7 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	Ports P16, P17, port PA6, port PB0 (5 V tolerant)	V_{IH}	VCC × 0.8	—	5.8	V	
	Ports P03, P05, ports P14, P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC0 to PC7, ports PE0 to PE7, ports PH0 to PH3, PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	All pins		–0.3	—	VCC × 0.2		
	All pins	ΔV_T	VCC × 0.01	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		

Table 5.5 DC Characteristics (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input leakage current	RES#, MD, port P35, port PH7	$\lvert I_{in} \rvert$	—	—	1.0	µA	V_{in} = 0 V, VCC
Three-state leakage current (off-state)	Ports for 5 V tolerant	$\lvert I_{TSI} \rvert$	—	—	1.0	µA	V_{in} = 0 V, 5.8 V
	Pins other than above		—	—	1.0		V_{in} = 0 V, VCC
Input capacitance	All input pins (except for port P16, port P35)	C_{in}	—	—	15	pF	V_{in} = 0 mV, Frequency: 1 MHz, T_a = 25°C
	Port P16, port P35		—	—	30		

Table 5.6 DC Characteristics (4)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input pull-up resistor	All ports (except for port P35, port PH7)	R_U	10	20	100	kΩ	V_{in} = 0 V

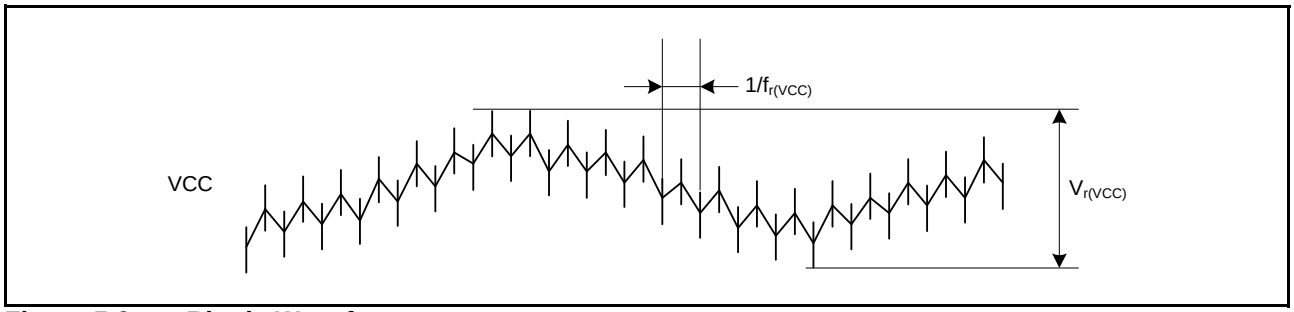


Figure 5.6 Ripple Waveform

Table 5.14 DC Characteristics (12)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Permissible error of VCL pin external capacitance	C_{VCL}	1.4	4.7	7.0	µF	

Note: The recommended capacitance is 4.7 µF. Variations in connected capacitors should be within the above range.

Table 5.15 Permissible Output Currents (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V,
T_a = –40 to +85°C (D version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OL}	2.4	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		30	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		30	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		30	
	Total of all output pins		60	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OH}	–0.1	
	Ports other than above		–4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		–0.1	
	Ports other than above		–4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OH}	–0.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		–10	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		–15	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		–15	
	Total of all output pins		–40	

Note: Do not exceed the permissible total supply current.

Table 5.16 Permissible Output Currents (2)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V,
T_a = –40 to +105°C (G version)

Item		Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OL}	0.4	mA
	Ports other than above		8.0	
Permissible output low current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		0.4	
	Ports other than above		8.0	
Permissible output low current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OL}	1.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		20	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		20	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		20	
	Total of all output pins		40	
Permissible output high current (average value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7	I_{OH}	–0.1	
	Ports other than above		–4.0	
Permissible output high current (maximum value per pin)	Ports P40 to P44, P46, ports PJ6, PJ7		–0.1	
	Ports other than above		–4.0	
Permissible output high current	Total of ports P40 to P44, P46, ports PJ6, PJ7	ΣI_{OH}	–0.6	
	Total of ports P03, P05, ports P26, P27, ports P30, P31		–10	
	Total of ports P14 to P17, port P32, ports P54, P55, ports PB0, PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PH0 to PH3		–15	
	Total of ports PA0, PA1, PA3, PA4, PA6, ports PE0 to PE7		–15	
	Total of all output pins		–40	

Note: Do not exceed the permissible total supply current.

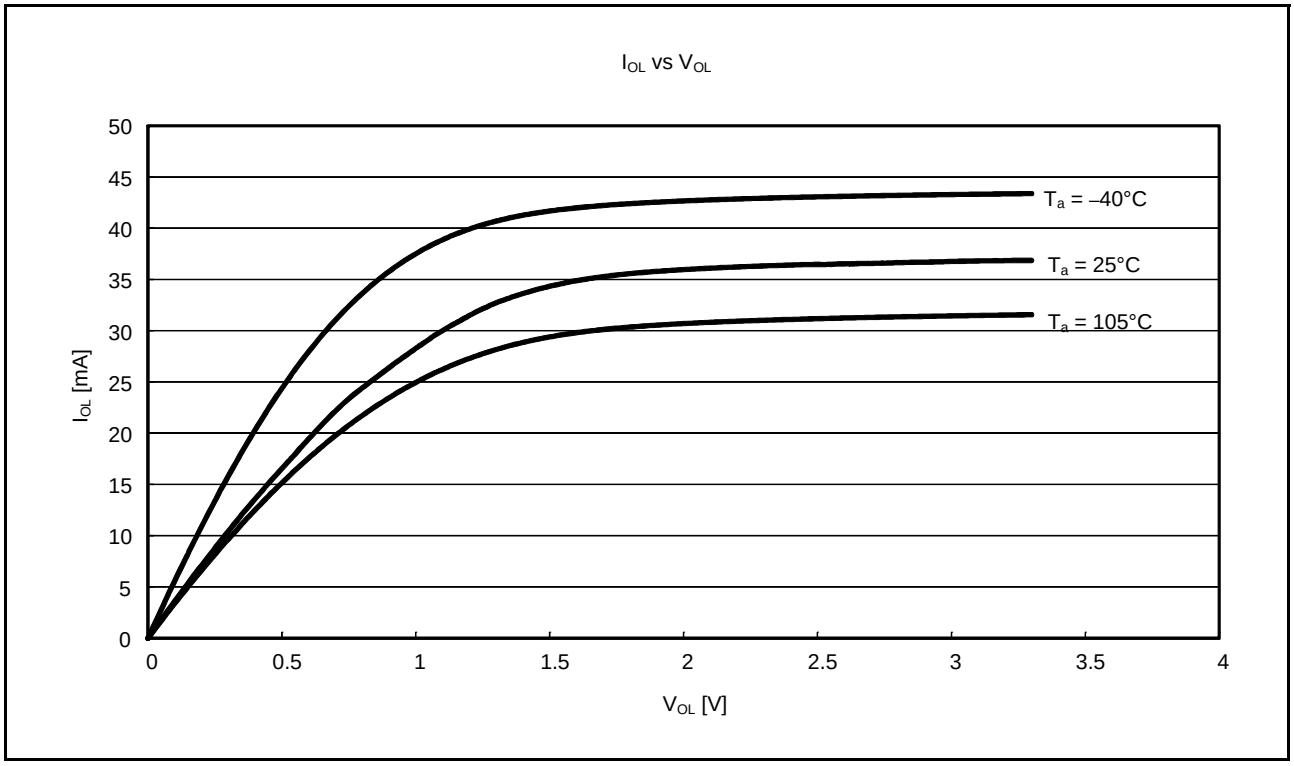


Figure 5.13 V_{OL} and I_{OL} Temperature Characteristics of RIIC Output Pin at VCC = 3.3 V (Reference Data)

5.3.5 Timing of On-Chip Peripheral Modules

Table 5.30 Timing of On-Chip Peripheral Modules (1)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Max.	Unit*1	Test Conditions
I/O ports	Input data pulse width			t_{PRW}	1.5	—	t_{Pcyc}	Figure 5.32
MTU2	Input capture input pulse width		Single-edge setting	t_{TICW}	1.5	—	t_{Pcyc}	Figure 5.33
			Both-edge setting		2.5	—		
	Timer clock pulse width		Single-edge setting	t_{TCKWH}, t_{TCKWL}	1.5	—	t_{Pcyc}	Figure 5.34
			Both-edge setting		2.5	—		
			Phase counting mode		2.5	—		
SCI	Input clock cycle		Asynchronous	t_{Scyc}	4	—	t_{Pcyc}	Figure 5.35
			Clock synchronous		6	—		
	Input clock pulse width			t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time			t_{SCKr}	—	20	ns	
	Input clock fall time			t_{SCKf}	—	20	ns	
	Output clock cycle		Asynchronous	t_{Scyc}	16	—	t_{Pcyc}	Figure 5.36 C = 30 pF
			Clock synchronous		4	—		
	Output clock pulse width			t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time			t_{SCKr}	—	20	ns	
	Output clock fall time			t_{SCKf}	—	20	ns	
	Transmit data delay time (master)	Clock synchronous		t_{TXD}	—	40	ns	
	Transmit data delay time (slave)	Clock synchronous	2.7 V or above		—	65	ns	
			1.8 V or above		—	100	ns	
	Receive data setup time (master)	Clock synchronous	2.7 V or above	t_{RXS}	65	—	ns	
			1.8 V or above		90	—	ns	
	Receive data setup time (slave)	Clock synchronous			40	—	ns	
	Receive data hold time	Clock synchronous		t_{RXH}	40	—	ns	
A/D converter	Trigger input pulse width			t_{TRGW}	1.5	—	t_{Pcyc}	Figure 5.37
CAC	CACREF input pulse width		$t_{Pcyc} \le t_{cac}$*2	t_{CACREF}	4.5 t_{cac} + 3 t_{Pcyc}	—	ns	
			$t_{Pcyc} > t_{cac}$*2		5 t_{cac} + 6.5 t_{Pcyc}			
CLKOUT	CLKOUT pin output cycle*4		VCC = 2.7 V or above	t_{Ccyc}	125	—	ns	
			VCC = 1.8 V or above		250			
	CLKOUT pin high pulse width*3		VCC = 2.7 V or above	t_{CH}	35	—	ns	
			VCC = 1.8 V or above		70			
	CLKOUT pin low pulse width*3		VCC = 2.7 V or above	t_{CL}	35	—	ns	
			VCC = 1.8 V or above		70			
	CLKOUT pin output rise time		VCC = 2.7 V or above	t_{Cr}	—	15	ns	
			VCC = 1.8 V or above			30		
	CLKOUT pin output fall time		VCC = 2.7 V or above	t_{Cf}	—	15	ns	
			VCC = 1.8 V or above			30		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. t_{cac}: CAC count clock source cycle
Note 3. When the LOCO is selected as the clock output source (CKOCR.CKOSEL[2:0] bits = 000b), set the clock output division ratio selection to divided by 2 (CKOCR.CKODIV[2:0] bits = 001b).
Note 4. When the XTAL external clock input or an oscillator is used with divided by 1 (CKOCR.CKOSEL[2:0] bits = 010b and CKOCR.CKODIV[2:0] bits = 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

Table 5.32 Timing of On-Chip Peripheral Modules (3)

Conditions: 1.8 V ≤ VCC ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, T_a = –40 to +105°C, C = 30 pF

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)		t_{SPcyc}	4	65536	t_{Pcyc}	Figure 5.39
	SCK clock cycle input (slave)			6	65536		
	SCK clock high pulse width		t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width		t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise/fall time		t_{SPCKr}, t_{SPCKf}	—	20	ns	
	Data input setup time (master)	2.7 V or above	t_{SU}	65	—	ns	Figure 5.40, Figure 5.42
		1.8 V or above		95	—		
	Data input setup time (slave)			40	—		
	Data input hold time		t_H	40	—	ns	
	SS input setup time		t_{LEAD}	3	—	t_{Pcyc}	
	SS input hold time		t_{LAG}	3	—	t_{Pcyc}	
	Data output delay time (master)		t_{OD}	—	40	ns	
	Data output delay time (slave)	2.7 V or above		—	65		
		1.8 V or above		—	85		
	Data output hold time (master)	2.7 V or above	t_{OH}	–10	—	ns	
		1.8 V or above		–20	—		
	Data output hold time (slave)			–10	—		
	Data rise/fall time		t_{Dr}, t_{Df}	—	20	ns	
	SS input rise/fall time		t_{SSLr}, t_{SSLf}	—	20	ns	
	Slave access time		t_{SA}	—	6	t_{Pcyc}	Figure 5.44, Figure 5.45
	Slave output release time		t_{REL}	—	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLK cycle

Table 5.34 Timing of On-Chip Peripheral Modules (5)

Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V, fPCLKB ≤ 32 MHz, T_a = –40 to +105°C

Item		Symbol	Min.	Max.	Unit	Test Conditions
Simple I²C (Standard mode)	SDA0 input rise time	t_{Sr}	—	1000	ns	Figure 5.46
	SDA0 input fall time	t_{Sf}	—	300	ns	
	SDA0 input spike pulse removal time	t_{SP}	0	4 × t_{pcyc}*1	ns	
	Data input setup time	t_{SDAS}	250	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	
Simple I²C (Fast mode)	SCL0, SDA0 input rise time	t_{Sr}	—	300	ns	Figure 5.46
	SCL0, SDA0 input fall time	t_{Sf}	—	300	ns	
	SCL0, SDA0 input spike pulse removal time	t_{SP}	0	4 × t_{pcyc}*1	ns	
	Data input setup time	t_{SDAS}	100	—	ns	
	Data input hold time	t_{SDAH}	0	—	ns	
	SCL0, SDA0 capacitive load	C_b	—	400	pF	

Note: t_{Pcyc}: PCLK cycle

Note 1. This applies when the SMR.CKS[1:0] bits = 00b and the SNFR.NFCS[2:0] bits = 010b while the SNFR.NFE bit = 1 and the digital filter is enabled.

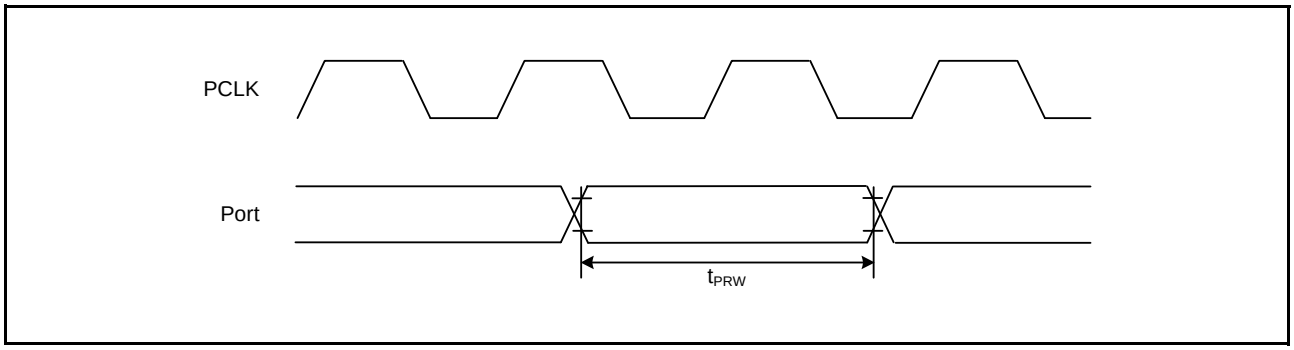


Figure 5.32 I/O Port Input Timing

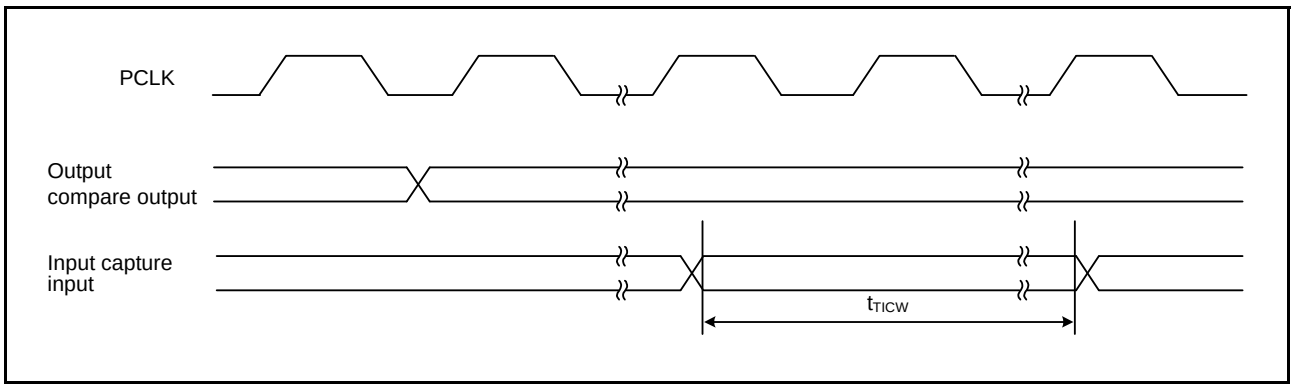


Figure 5.33 MTU2 Input/Output Timing

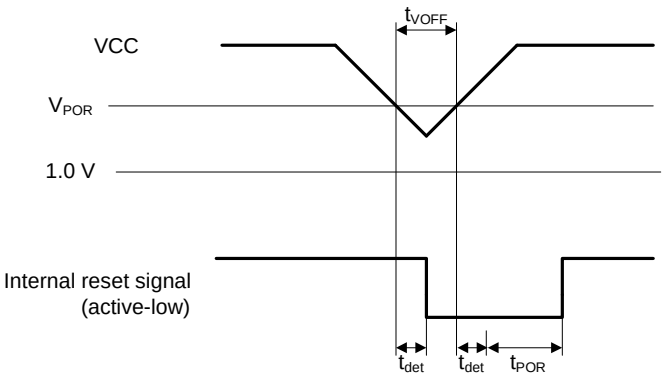
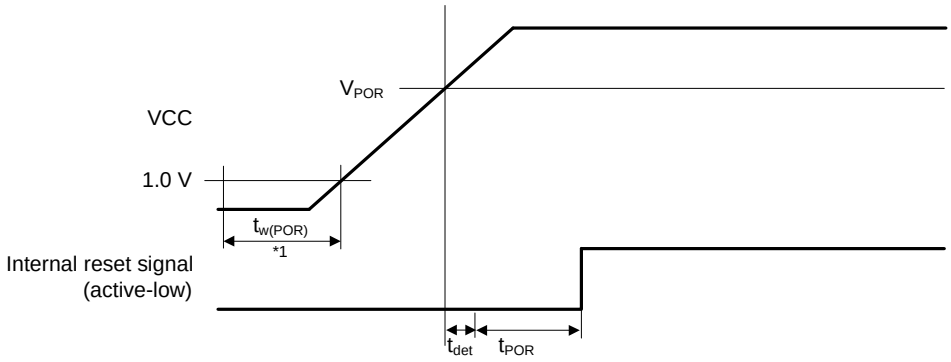


Figure 5.49 Voltage Detection Reset Timing



Note 1. $t_{w(por)}$ is the time required for a power-on reset to be enabled while the external power VCC is being held below the valid voltage (1.0 V).
When VCC turns on, maintain $t_{w(por)}$ for 1.0 ms or more.

Figure 5.50 Power-On Reset Timing

5.8 ROM (Flash Memory for Code Storage) Characteristics

Table 5.44 ROM (Flash Memory for Code Storage) Characteristics (1)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N_{PEC}	1000	—	—	Times	
Data hold time	After 1000 times of N_{PEC}	t_{DRP}	20*2, *3	—	—	Year	T_a = +85°C

Note 1. Definition of reprogram/erase cycle: The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 1000), erasing can be performed n times for each block. For instance, when 4-byte programming is performed 256 times for different addresses in 1-Kbyte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).
Note 2. Characteristic when using the flash memory programmer and the self-programming library provided from Renesas Electronics.
Note 3. This result is obtained from reliability testing.

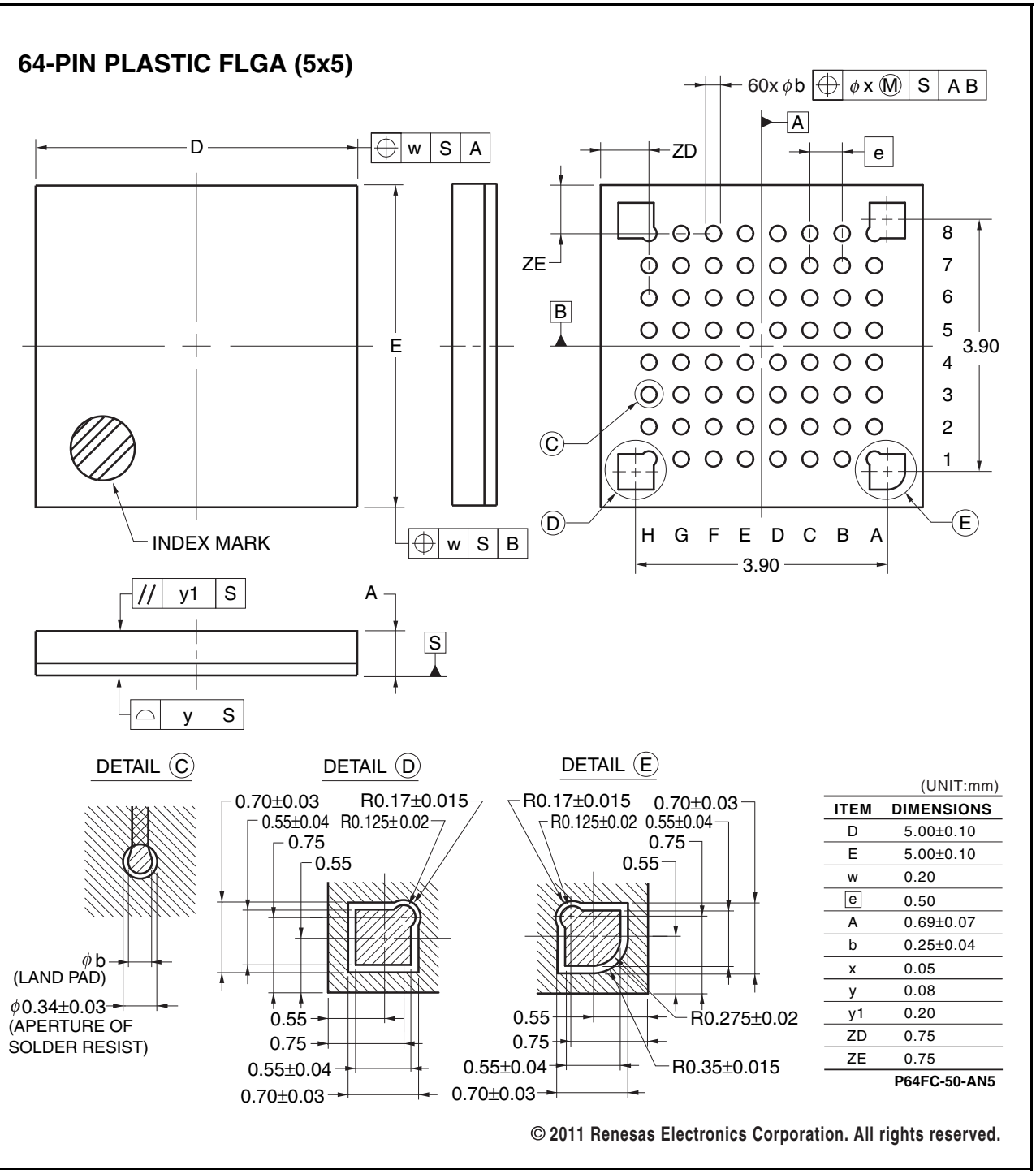
Table 5.45 ROM (Flash Memory for Code Storage) Characteristics (2)

High-speed operating mode Conditions: 2.7 V ≤ VCC ≤ 3.6 V, 2.7 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +105°C

Item		Symbol	FCLK = 1 MHz			FCLK = 32 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	4-byte	t_{P4}	—	103	931	—	52	489	µs
Erasure time	1-Kbyte	t_{E1K}	—	8.23	267	—	5.48	214	ms
	128-Kbyte	t_{E128K}	—	203	463	—	20	228	ms
Blank check time	4-byte	t_{BC4}	—	—	48	—	—	15.9	µs
	1-Kbyte	t_{BC1K}	—	—	1.58	—	—	0.127	ms
Erase operation forcible stop time		t_{SED}	—	—	21.6	—	—	12.8	µs
Start-up area switching setting time		t_{SAS}	—	12.6	543	—	6.16	432	ms
Access window time		t_{AWS}	—	12.6	543	—	6.16	432	ms
ROM mode transition wait time 1		t_{DIS}	2	—	—	2	—	—	µs
ROM mode transition wait time 2		t_{MS}	5	—	—	5	—	—	µs

Note: Does not include the time until each operation of the flash memory is started after instructions are executed by software.
Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: The frequency accuracy of FCLK should be ±3.5%. Confirm the frequency accuracy of the clock source.



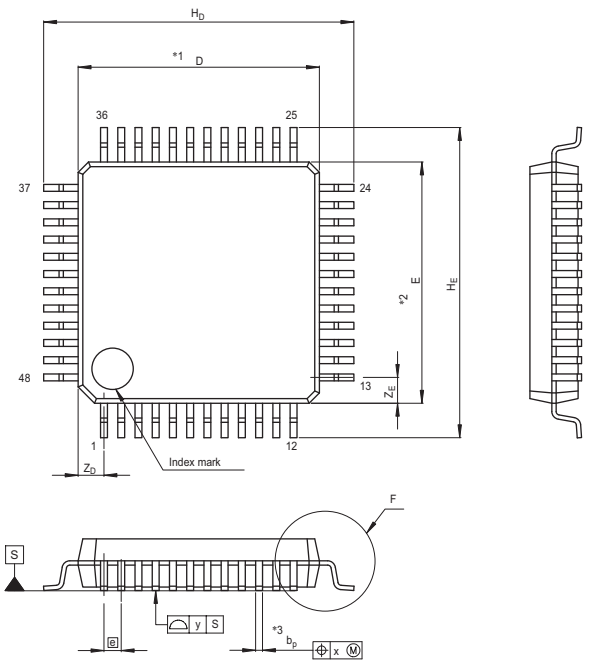
(UNIT:mm)

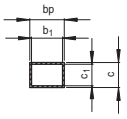
ITEM	DIMENSIONS
D	5.00±0.10
E	5.00±0.10
w	0.20
e	0.50
A	0.69±0.07
b	0.25±0.04
x	0.05
y	0.08
y1	0.20
ZD	0.75
ZE	0.75

P64FC-50-AN5

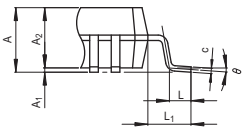
Figure C 64-Pin WFLGA (PWLG0064KA-A)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP48-7x7-0.50	PLQP0048KB-A	48P6Q-A	0.2g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.4	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.17	0.22	0.27
b_1	—	0.20	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.10
Z_D	—	0.75	—
Z_E	—	0.75	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure D 48-Pin LFQFP (PLQP0048KB-A)

NOTES FOR CMOS DEVICES

(1) VOLTAGE APPLICATION WAVEFORM AT INPUT PIN: Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between VIL (MAX) and VIH (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between VIL (MAX) and VIH (MIN).

(2) HANDLING OF UNUSED INPUT PINS: Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

(3) PRECAUTION AGAINST ESD: A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

(4) STATUS BEFORE INITIALIZATION: Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

(5) POWER ON/OFF SEQUENCE: In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current. The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

(6) INPUT OF SIGNAL DURING POWER OFF STATE : Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.